Impressive turn-out for the virtual 70th ECTC

Eric Perfecto, 71st ECTC Publicity Chair

The Coronavirus pandemic necessitated the IEEE Electronic, Components and Technology Conference (ECTC) to move into a virtual format this year. Due to the generous support for IEEE/EPS and our corporate sponsors, the in-person event was transformed into a free-to-attend on-demand virtual conference. Over 7,700 individuals took advantage of this offer and attended the virtual conference, which consisted of over 400 presentations organized into 45 technical sessions and 7 special invited sessions. The virtual conference opened on June 3, 2020 and after one-week extension closed on July 7, 2020. The attendance covered 55 countries and over 28,000 hours of streamed content viewed.

The technical program can be seen here: https://www.ectc.net/program/index.cfm. Table 1 shows the top ten most attended sessions. Advanced packaging technologies, such as Wafer-level Fan-out packaging and 3D, had the highest attendance of the technical and special sessions, with special mention to the keynote lecture from Dr. Douglas Yu of TSMC titled "Innovative Heterogeneous Integration Technologies Initiate a New Era" which got almost over 2,000 views.

70th ECTC Technical Session	Attendance
Fan-Out Technologies for System Integration	1,062
Innovation on WLCSP and 3D Packaging	838
Advances in Packaging at the Wafer/Panel Level	802
2.5D and 3D Technology Enabling High Performance Computing	714
Advanced Bonding Methods and Processing	687
High-Density RDL for Advanced Interconnects	661
Antenna-in-Package for 5G and Radar Systems	647
Manufacturing Techniques for Advanced Packaging	570
Embedded and Heterogeneous Integration	556
High Density Fan-Out Technology	533

Table 1. Top ten most attended technical sessions at the 70th ECTC. (Chris Bower)

Many thanks to the over 250 technical experts who volunteer on the program committee, and to the authors wh0 presented their work at ECTC. This year, we send a special thank you to the IEEE Event Emergency Response Team and the IEEE Meetings, Conferences and Events (MCE) group for helping us navigate both the cancellation of the in-person event and the creation of the virtual event.

Planning is already underway for the 71st ECTC, which will be held June 1-4, 2021, at the Sheraton San Diego Hotel & Marina in San Diego, CA. The first call-for-papers has been issued, the abstract submission process will open on August 15, 2020 and abstracts must be received by October 4, 2020. For more information visit ectc.net.